

Mating cycles : max. 500

Recommended configuration of plated through holes :

<i>Tin plated PCB (HAL)</i> acc. EN 60 352-5	Hole-Ø	1.15 ^{±0.025} mm
	Cu	min. 25 µm
	Sn	max. 15 µm
	Plated hole-Ø	0.94-1.09 mm
<i>Chemical tin plated PCB</i>	Hole-Ø	1.15 ^{±0.025} mm
	Cu	min. 25 µm
	Sn	min. 0.8 µm
	Plated hole-Ø	1.00-1.10 mm
<i>Au / Ni plated PCB</i>	Hole-Ø	1.15 ^{±0.025} mm
	Cu	min. 25 µm
	Ni	3-7 µm
	Au	0.05-0.12 µm
	Plated hole-Ø	1.00-1.10 mm
<i>Silver plated PCB</i>	Hole-Ø	1.15 ^{±0.025} mm
	Cu	min. 25 µm
	Ag	0.1-0.3 µm
	Plated hole-Ø	1.00-1.10 mm
<i>OSP copper plated PCB</i>	Hole-Ø	1.15 ^{±0.025} mm
	Cu	min. 25 µm
	Plated hole-Ø	1.00-1.10 mm

PCB board thickness: ≥ 1.6 mm

Mating force : ≤ 10 N/contact

Withdrawal force : > 1 N/contact

Mating distance : 12.5 ... 15 mm

Wiping length : 2.5 mm

Acceptable radial mating offset : max. ± 1.5 mm

